

# BGF101

## USB ESD Protection

AIM  
Discrete Semiconductors



Never stop thinking.

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**BGF101**

**Data sheet**

**Revision History:** **2005-06-01**

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Previous Version: 2004-03-08

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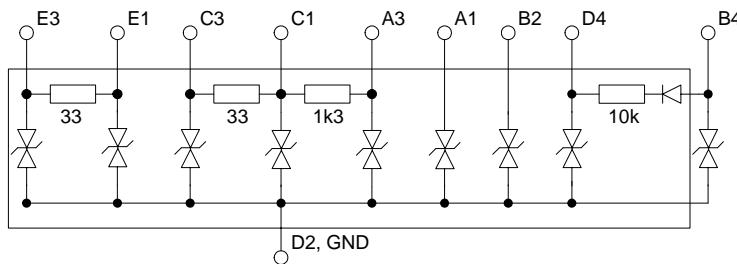
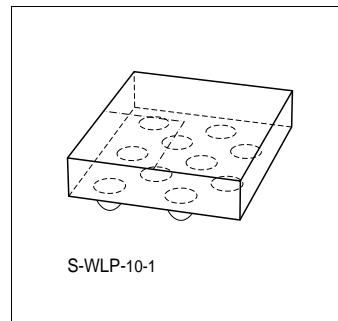
Page	Subjects (major changes since last revision)
all	Preliminary status removed

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## Features

- ESD protection circuit for full speed USB interfaces
- Integrated ESD protection according to IEC61000-4-2 up to 15 kV contact discharge
- Green wafer level package with SnAgCu balls
- 500  $\mu\text{m}$  diagonal ball pitch
- 300  $\mu\text{m}$  ball diameter



## Description

The BGF101 is an ESD protection circuit for a full speed USB interface (12 Mbit/sec). External pins are protected against ESD up to 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green package with a size of only 1.65 mm x 2.0 mm and a total height of 0.65 mm.

Type	Package	Marking	Chip
BGF101	WLP-10-1	GF101	N0706

## Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage at all pins to GND	$V_P$	7	V
Operating temperature range	$T_{OP}$	-40 ... +85	°C
Storage temperature range	$T_{STG}$	-65 ... +150	°C
Summed up input power for all pins, $T_S < 70^\circ\text{C}$	$P_{IN}$	60	mW
Electrostatic discharge according to IEC61000-4-2 <sup>1)</sup> at pins A1, A3, B2, C1, C3, D4, E1, E3 at pin B2	$V_{ESD}$	15 8	kV

<sup>1)</sup> Contact discharge

 Electrical Characteristics at  $T_A=25^\circ\text{C}$ 

Parameter	Symbol	min.	typ.	max.	Unit
Resistors					
R1, R2	$R_{1,2}$	31.3	33	34.7	Ω
R3	$R_3$	1235	1300	1365	Ω
R4 <sup>1)</sup>	$R_4$	9.5	10	10.5	kΩ
Temperature coefficient <sup>2)</sup>	$ TCR $		100	130	ppm/K
ESD protection diodes					
Reverse current	$I_R$				
$V_R = 3\text{ V}$ to GND			1	100	nA
$V_R = 7\text{ V}$ to GND			1	100	μA
Pin capacitance					
Cap. of pins A3, C1, C3, E1, E3 to GND	$C_T$				pF
$V_R = 0\text{ V}$ <sup>3)</sup>			48	53	
Diode D1					
Forward voltage	$V_F$				
$I_F = 1\text{ μA}$			0.27	0.35	V

<sup>1)</sup> in production not tested separately, but correlated to R3

<sup>2)</sup> averaged over full operating temperature range from -40 to +85°C, see figure 2

<sup>3)</sup> not subject to production test, verified by design/ characterization

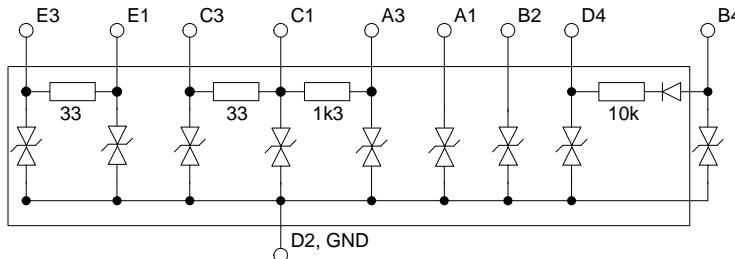


Fig.1: Schematic

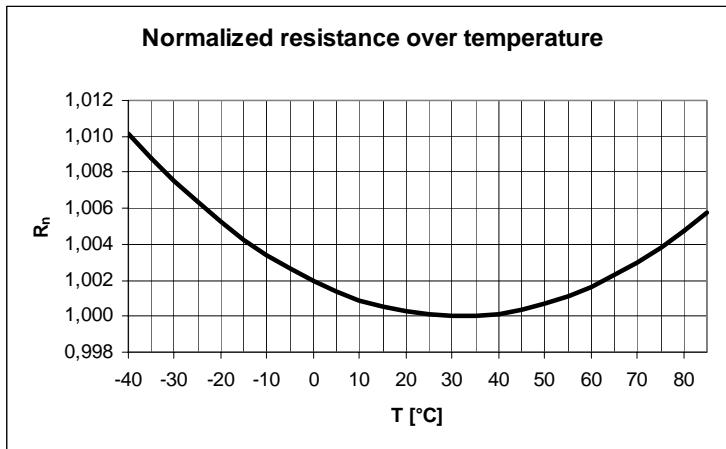
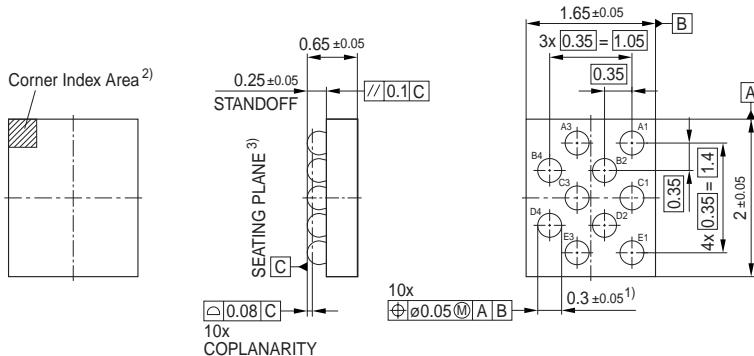


Fig.2: Normalized resistance over temperature

## Package Outline



1) Dimension is measured at the maximum ball diameter, parallel to primary datum C

2) A1 corner identified by marking

3) Primary datum C and seating plane are defined by the domed crowns of the balls

GWL09661

**WLP-10-1**